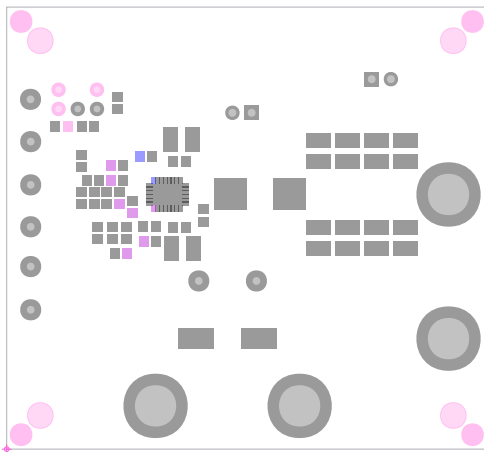


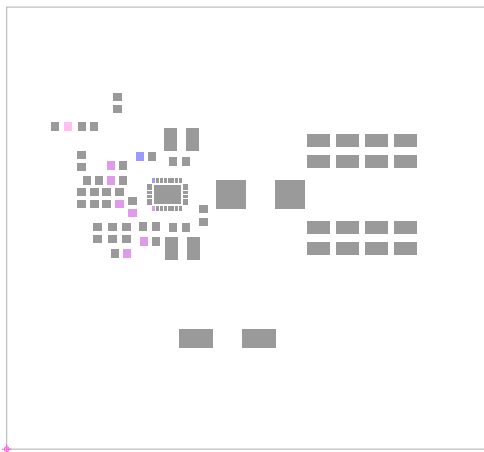
ASSEMBLY TOP

RENESAS  
02/22/2021  
RTKA211651DE000BU\_B



SOLDER MASK TOP

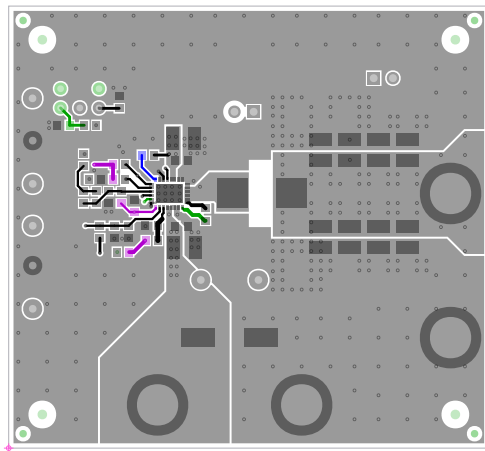
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SOLDER PASTE TOP

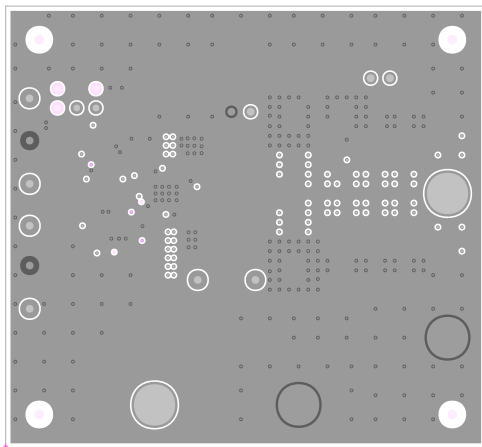
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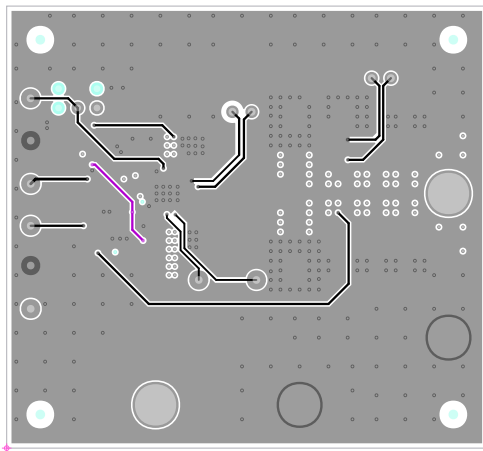
TOP LAYER COMPONENT SIDE

RENESAS  
02/22/2021  
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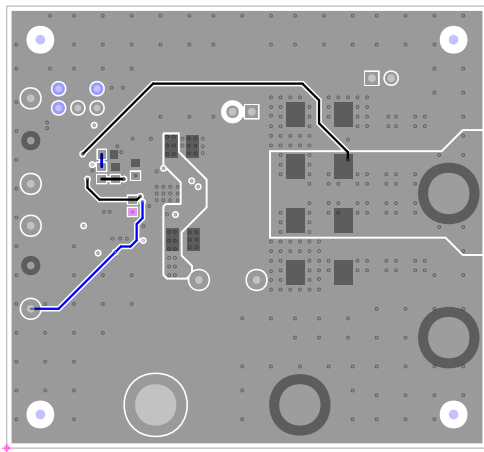
LAYER 2

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LAYER 3

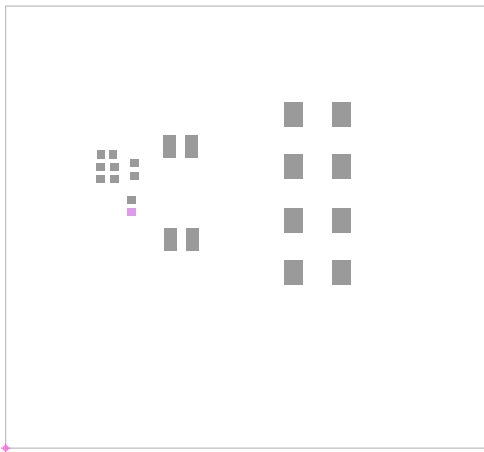
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BOTTOM COMPONENT SIDE

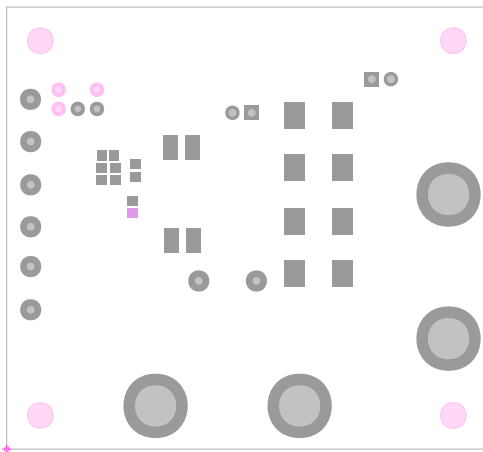
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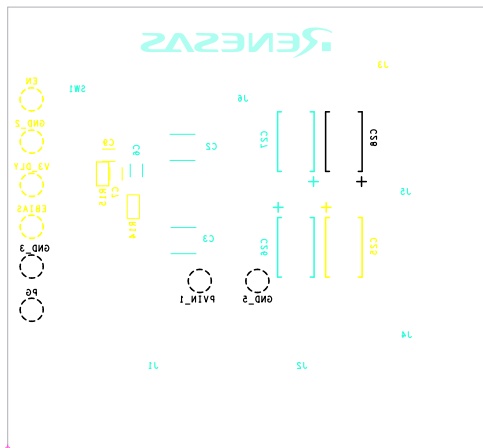
SOLDER PASTE BOTTOM

RENEAS  
02/22/2021  
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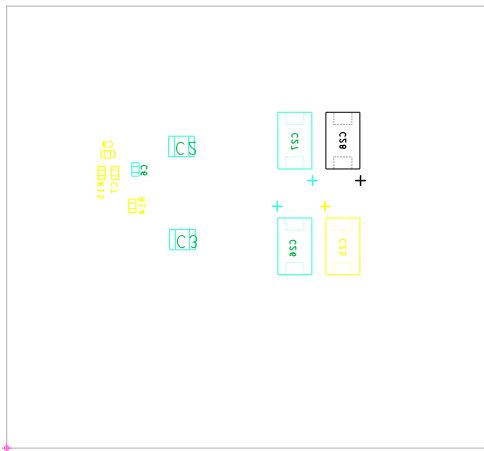
SOLDER MASK BOTTOM

RENESAS  
02/22/2021  
RTKA211651DE0000BU\_B



SILK SCREEN BOTTOM

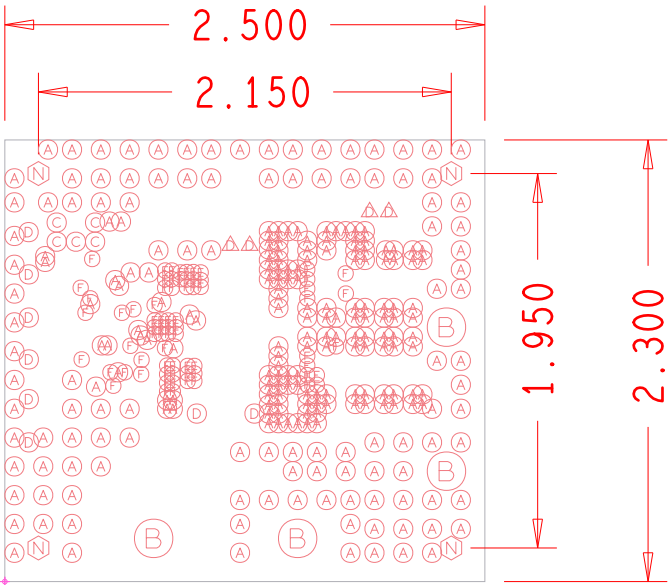
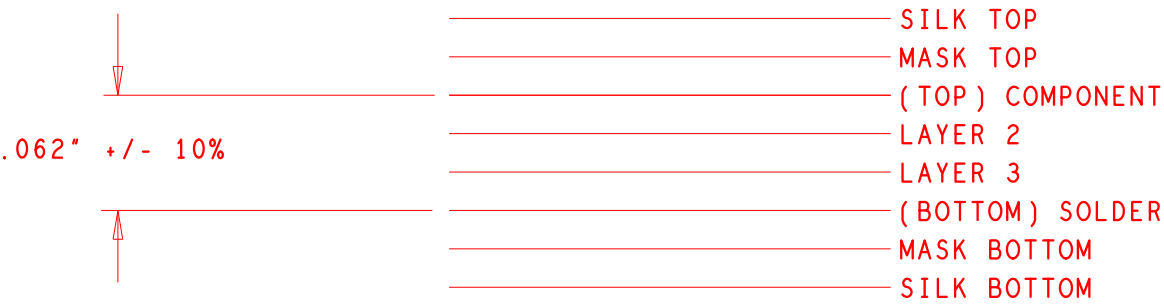
RENEASAS  
 02/22/2021  
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ASSEMBLY BOTTOM

RENESAS  
02/22/2021  
RTKA211651DE0000BU\_B

PHYSICAL BOARD DIMENSIONS



DRILL

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
A	10.0	PLATED	255
E	11.0	PLATED	71
C	35.0	PLATED	5
D	40.0	PLATED	8
A	41.0	PLATED	4
B	215.0	PLATED	4
N	128.0	NON-PLATED	4

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 1\_OZ COPPER INNER LAYERS AND 2\_OZ OUTER LAYERS
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED RTKA211651DE0000BU-B\_IPC356.IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. ALL 11 MIL VIA'S ARE TO BE THERMAL EPOXY FILLED AND CAPPED.
12. WAIVE IPC610 SPEC FOR SOLDER FILL VIA (VIA-IN-PAD).
13. ALL VIAS TO BE TENTED. NO EXPOSED COPPER PADS ON ANY VIAS TOP OR BOTTOM EXCEPT VIAS IN SMT PADS.

Drawn By: AMNAT YAKAMNA	Date Drawn: 02/22/2021	Engineer: KRISHNA MAINALI	
Released By:	Date Released:	RAA211651 EVAL BOARD PCB LAYOUT	
Updated By:	Date Updated:		
RENESAS		MASK#	HDWR ID
		REV. B	
FILENAME: RTKA211651DE0000BU_C_12_16_2019			SHEET 1 of 1